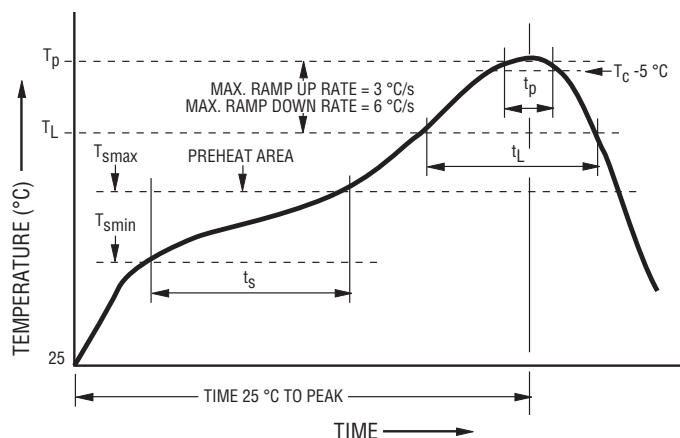
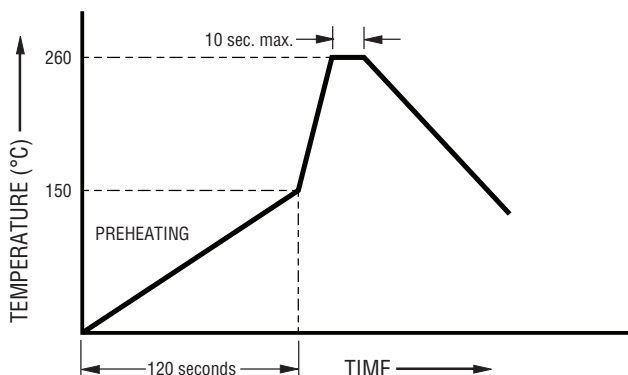


Solder Reflow Recommendations

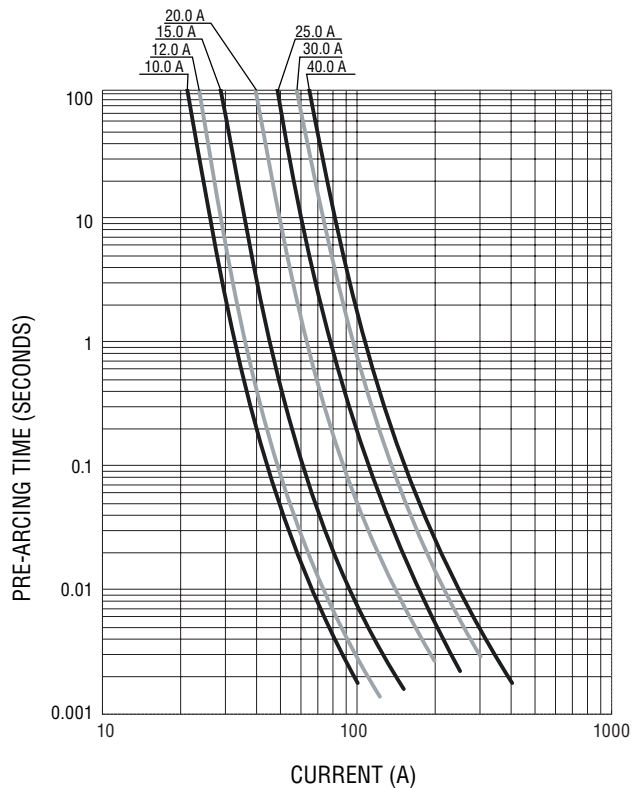
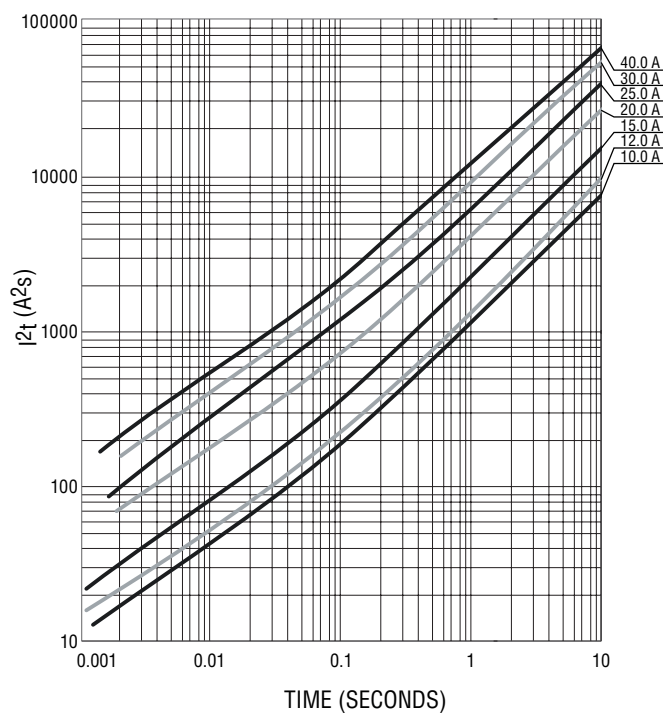
Profile Feature	Pb-Free Assembly
Preheat / Soak:	
Temperature Min. (T_{smin})	150 °C
Temperature Max. (T_{smax})	200 °C
Time (t_s) from (T_{smin} to T_{smax})	60~120 seconds
Ramp Up Rate (T_L to T_p)	3 °C / second max.
Liquidous Temperature (T_L)	217 °C
Time (t_L) maintained above T_L	60~150 seconds
Peak Package Body Temperature (T_p)	260 °C
Time (t_p)* within 5 °C of the specified classification temperature (T_C)	30 seconds*
Ramp Down Rate (T_p to T_L)	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

Recommended Temperature Profile for Wave Soldering

Wave soldering is suitable for 1206 size models.

Average Pre-Arcing Time vs. Current Curves

Average I^2t vs. t Curves

REV. A 06/18

Specifications are subject to change without notice.

Users should verify actual device performance in their specific applications.

The products described herein and this document are subject to specific legal disclaimers as set forth on the last page of this document, and at www.bourns.com/docs/legal/disclaimer.pdf.